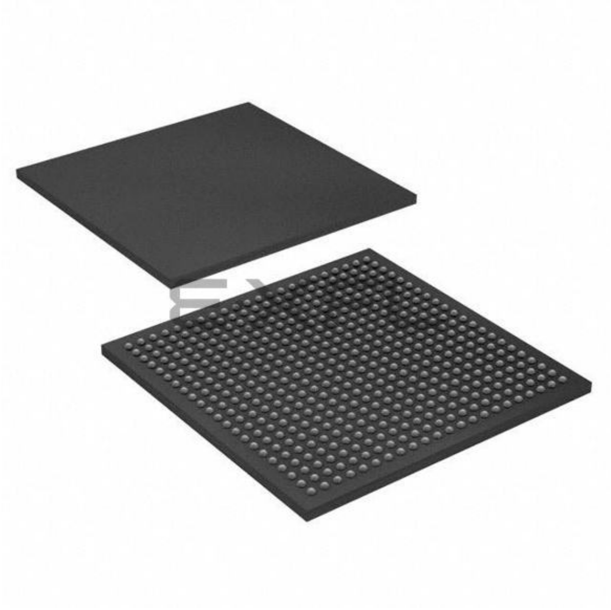

Embedded - System On Chip (SoC): The Heart of Modern Embedded Systems

Embedded - System On Chip (SoC) refers to an integrated circuit that consolidates all the essential components of a computer system into a single chip. This includes a microprocessor, memory, and other peripherals, all packed into one compact and efficient package. SoCs are designed to provide a complete computing solution, optimizing both space and power consumption, making them ideal for a wide range of embedded applications.

What are Embedded - System On Chip (SoC)?

System On Chip (SoC) integrates multiple functions of a computer or electronic system onto a single chip. Unlike traditional multi-chip solutions, SoCs combine a central

Details	
Product Status	Active
Architecture	MCU, FPGA
Core Processor	Dual ARM® Cortex®-A9 MPCore™ with CoreSight™
Flash Size	-
RAM Size	64KB
Peripherals	DMA, POR, WDT
Connectivity	CANbus, EBI/EMI, Ethernet, I²C, MMC/SD/SDIO, SPI, UART/USART, USB OTG
Speed	600MHz
Primary Attributes	FPGA - 85K Logic Elements
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	484-FBGA
Supplier Device Package	484-UBGA (19x19)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5cseba5u19c8n

Contents

HPS Power Supply Operating Conditions

Table 6. HPS Power Supply Operating Conditions for Cyclone V SX and ST Devices

This table lists the steady-state voltage and current values expected from Cyclone V system-on-a-chip (SoC) devices with Arm*-based hard processor system (HPS). Power supply ramps must all be strictly monotonic, without plateaus. Refer to the *Recommended Operating Conditions for Cyclone V Devices* table for the steady-state voltage values expected from the FPGA portion of the Cyclone V SoC devices.

Symbol	Description	Condition	Minimum(11)	Typical	Maximum(11)	Unit
V_{CC_HPS}	HPS core voltage and periphery circuitry power supply	—	1.07	1.1	1.13	V
V_{CCPD_HPS} (12)	HPS I/O pre-driver power supply	3.3 V	3.135	3.3	3.465	V
		3.0 V	2.85	3.0	3.15	V
		2.5 V	2.375	2.5	2.625	V
V_{CCIO_HPS}	HPS I/O buffers power supply	3.3 V	3.135	3.3	3.465	V
		3.0 V	2.85	3.0	3.15	V
		2.5 V	2.375	2.5	2.625	V
		1.8 V	1.71	1.8	1.89	V
		1.5 V	1.425	1.5	1.575	V
		1.35 V (13)	1.283	1.35	1.418	V
		1.2 V	1.14	1.2	1.26	V
$V_{CCRSTCLK\_HPS}$	HPS reset and clock input pins power supply	3.3 V	3.135	3.3	3.465	V
		3.0 V	2.85	3.0	3.15	V
		2.5 V	2.375	2.5	2.625	V

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(11) The power supply value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

(12) V_{CCPD_HPS} must be 2.5 V when V_{CCIO_HPS} is 2.5, 1.8, 1.5, or 1.2 V. V_{CCPD_HPS} must be 3.0 V when V_{CCIO_HPS} is 3.0 V. V_{CCPD_HPS} must be 3.3 V when V_{CCIO_HPS} is 3.3 V.

(13) V_{CCIO_HPS} 1.35 V is supported for HPS row I/O bank only.

OCT Without Calibration Resistance Tolerance Specifications

Table 10. OCT Without Calibration Resistance Tolerance Specifications for Cyclone V Devices

This table lists the Cyclone V OCT without calibration resistance tolerance to PVT changes.

Symbol	Description	Condition (V)	Resistance Tolerance			Unit
			–C6	–I7, –C7	–C8, –A7	
25-Ω R_S	Internal series termination without calibration (25-Ω setting)	V_{CCIO} = 3.0, 2.5	±30	±40	±40	%
25-Ω R_S	Internal series termination without calibration (25-Ω setting)	V_{CCIO} = 1.8, 1.5	±30	±40	±40	%
25-Ω R_S	Internal series termination without calibration (25-Ω setting)	V_{CCIO} = 1.2	±35	±50	±50	%
50-Ω R_S	Internal series termination without calibration (50-Ω setting)	V_{CCIO} = 3.0, 2.5	±30	±40	±40	%
50-Ω R_S	Internal series termination without calibration (50-Ω setting)	V_{CCIO} = 1.8, 1.5	±30	±40	±40	%
50-Ω R_S	Internal series termination without calibration (50-Ω setting)	V_{CCIO} = 1.2	±35	±50	±50	%
100-Ω R_D	Internal differential termination (100-Ω setting)	V_{CCIO} = 2.5	±25	±40	±40	%

Figure 2. Equation for OCT Variation Without Recalibration

$$R_{OCT} = R_{SCAL}\left(1 + \left\langle\frac{dR}{dT} \times \Delta T\right\rangle \pm \left\langle\frac{dR}{dV} \times \Delta V\right\rangle\right)$$

The definitions for the equation are as follows:

- The R_{OCT} value calculated shows the range of OCT resistance with the variation of temperature and V_{CCIO}.
- R_{SCAL} is the OCT resistance value at power-up.
- ΔT is the variation of temperature with respect to the temperature at power up.

- ΔV is the variation of voltage with respect to the V_{CCIO} at power up.
- dR/dT is the percentage change of R_{SCAL} with temperature.
- dR/dV is the percentage change of R_{SCAL} with voltage.

OCT Variation after Power-Up Calibration

Table 11. OCT Variation after Power-Up Calibration for Cyclone V Devices

This table lists OCT variation with temperature and voltage after power-up calibration. The OCT variation is valid for a V_{CCIO} range of ±5% and a temperature range of 0°C to 85°C.

Symbol	Description	V_{CCIO} (V)	Value	Unit
dR/dV	OCT variation with voltage without recalibration	3.0	0.100	%/mV
		2.5	0.100	
		1.8	0.100	
		1.5	0.100	
		1.35	0.150	
		1.25	0.150	
		1.2	0.150	
dR/dT	OCT variation with temperature without recalibration	3.0	0.189	%/°C
		2.5	0.208	
		1.8	0.266	
		1.5	0.273	
		1.35	0.200	
		1.25	0.200	
		1.2	0.317	

I/O Standard	V_{CCIO} (V)			V_{REF} (V)			V_{TT} (V)		
	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max
SSTL-15 Class I, II	1.425	1.5	1.575	0.49 × V_{CCIO}	0.5 × V_{CCIO}	0.51 × V_{CCIO}	0.49 × V_{CCIO}	0.5 × V_{CCIO}	0.51 × V_{CCIO}
SSTL-135 Class I, II	1.283	1.35	1.418	0.49 × V_{CCIO}	0.5 × V_{CCIO}	0.51 × V_{CCIO}	0.49 × V_{CCIO}	0.5 × V_{CCIO}	0.51 × V_{CCIO}
SSTL-125 Class I, II	1.19	1.25	1.26	0.49 × V_{CCIO}	0.5 × V_{CCIO}	0.51 × V_{CCIO}	0.49 × V_{CCIO}	0.5 × V_{CCIO}	0.51 × V_{CCIO}
HSTL-18 Class I, II	1.71	1.8	1.89	0.85	0.9	0.95	—	$V_{CCIO}/2$	—
HSTL-15 Class I, II	1.425	1.5	1.575	0.68	0.75	0.9	—	$V_{CCIO}/2$	—
HSTL-12 Class I, II	1.14	1.2	1.26	0.47 × V_{CCIO}	0.5 × V_{CCIO}	0.53 × V_{CCIO}	—	$V_{CCIO}/2$	—
HSUL-12	1.14	1.2	1.3	0.49 × V_{CCIO}	0.5 × V_{CCIO}	0.51 × V_{CCIO}	—	—	—

Single-Ended SSTL, HSTL, and HSUL I/O Standards Signal Specifications

Table 17. Single-Ended SSTL, HSTL, and HSUL I/O Standards Signal Specifications for Cyclone V Devices

I/O Standard	$V_{IL(DC)}$ (V)		$V_{IH(DC)}$ (V)		$V_{IL(AC)}$ (V)	$V_{IH(AC)}$ (V)	V_{OL} (V)	V_{OH} (V)	I_{OL}(19) (mA)	I_{OH}(19) (mA)
	Min	Max	Min	Max	Max	Min	Max	Min		
SSTL-2 Class I	–0.3	V_{REF} – 0.15	V_{REF} + 0.15	V_{CCIO} + 0.3	V_{REF} – 0.31	V_{REF} + 0.31	V_{TT} – 0.608	V_{TT} + 0.608	8.1	–8.1
SSTL-2 Class II	–0.3	V_{REF} – 0.15	V_{REF} + 0.15	V_{CCIO} + 0.3	V_{REF} – 0.31	V_{REF} + 0.31	V_{TT} – 0.81	V_{TT} + 0.81	16.2	–16.2
SSTL-18 Class I	–0.3	V_{REF} – 0.125	V_{REF} + 0.125	V_{CCIO} + 0.3	V_{REF} – 0.25	V_{REF} + 0.25	V_{TT} – 0.603	V_{TT} + 0.603	6.7	–6.7
SSTL-18 Class II	–0.3	V_{REF} – 0.125	V_{REF} + 0.125	V_{CCIO} + 0.3	V_{REF} – 0.25	V_{REF} + 0.25	0.28	V_{CCIO} – 0.28	13.4	–13.4

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(19) To meet the I_{OL} and I_{OH} specifications, you must set the current strength settings accordingly. For example, to meet the SSTL15CI specification (8 mA), you should set the current strength settings to 8 mA. Setting at lower current strength may not meet the I_{OL} and I_{OH} specifications in the datasheet.

Differential I/O Standard Specifications

Table 20. Differential I/O Standard Specifications for Cyclone V Devices

Differential inputs are powered by V_{CCPD} which requires 2.5 V.

I/O Standard	V_{CCIO} (V)			V_{ID} (mV)[21]			$V_{ICM(DC)}$ (V)			V_{OD} (V)[22]			V_{OCM} (V)[22][23]		
	Min	Typ	Max	Min	Condition	Max	Min	Condition	Max	Min	Typ	Max	Min	Typ	Max
PCML	Transmitter, receiver, and input reference clock pins of high-speed transceivers use the PCML I/O standard. For transmitter, receiver, and reference clock I/O pin specifications, refer to *Transceiver Specifications for Cyclone V GX, GT, SX, and ST Devices* table.														
2.5 V LVDS[24]	2.375	2.5	2.625	100	V_{CM} = 1.25 V	—	0.05	D_{MAX} ≤ 700 Mbps	1.80	0.247	—	0.6	1.125	1.25	1.375
							1.05	D_{MAX} > 700 Mbps	1.55						
BLVDS[25][26]	2.375	2.5	2.625	100	—	—	—	—	—	—	—	—	—	—	—
RSDS (HIO)[27]	2.375	2.5	2.625	100	V_{CM} = 1.25 V	—	0.25	—	1.45	0.1	0.2	0.6	0.5	1.2	1.4
Mini-LVDS (HIO)[28]	2.375	2.5	2.625	200	—	600	0.300	—	1.425	0.25	—	0.6	1	1.2	1.4

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[21] The minimum V_{ID} value is applicable over the entire common mode range, V_{CM}.

[22] R_L range: $90 \leq R_L \leq 110\ \Omega$.

[23] This applies to default pre-emphasis setting only.

[24] For optimized LVDS receiver performance, the receiver voltage input range must be within 1.0 V to 1.6 V for data rate above 700 Mbps and 0.00 V to 1.85 V for data rate below 700 Mbps.

[25] There are no fixed V_{ICM}, V_{OD}, and V_{OCM} specifications for BLVDS. They depend on the system topology.

[26] For more information about BLVDS interface support in Intel devices, refer to *AN522: Implementing Bus LVDS Interface in Supported Intel Device Families*.

[27] For optimized RSDS receiver performance, the receiver voltage input range must be within 0.25 V to 1.45 V.

[28] For optimized mini-LVDS receiver performance, the receiver voltage input range must be within 0.300 V to 1.425 V.

I/O Standard	V_{CCIO} (V)			V_{ID} (mV)(21)			$V_{ICM(DC)}$ (V)			V_{OD} (V)(22)			V_{OCM} (V)(22)(23)		
	Min	Typ	Max	Min	Condition	Max	Min	Condition	Max	Min	Typ	Max	Min	Typ	Max
LVPECL(29)	—	—	—	300	—	—	0.60	$D_{MAX} \leq$ 700 Mbps	1.80	—	—	—	—	—	—
							1.00	$D_{MAX} >$ 700 Mbps	1.60						
SLVS	2.375	2.5	2.625	100	V_{CM} = 1.25 V	—	0.05	—	1.80	—	—	—	—	—	—
Sub-LVDS	2.375	2.5	2.625	100	V_{CM} = 1.25 V	—	0.05	—	1.80	—	—	—	—	—	—
HiSpi	2.375	2.5	2.625	100	V_{CM} = 1.25 V	—	0.05	—	1.80	—	—	—	—	—	—

Related Information

- AN522: Implementing Bus LVDS Interface in Supported Intel Device Families
  Provides more information about BLVDS interface support in Intel devices.
- Transceiver Specifications for Cyclone V GX, GT, SX, and ST Devices on page 25
  Provides the specifications for transmitter, receiver, and reference clock I/O pin.

Switching Characteristics

This section provides performance characteristics of Cyclone V core and periphery blocks.

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(21) The minimum V_{ID} value is applicable over the entire common mode range, V_{CM}.

(22) R_L range: $90 \leq R_L \leq 110\ \Omega$.

(23) This applies to default pre-emphasis setting only.

(29) For optimized LVPECL receiver performance, the receiver voltage input range must be within 0.85 V to 1.75 V for data rate above 700 Mbps and 0.45 V to 1.95 V for data rate below 700 Mbps.

Symbol/Description	Condition	Transceiver Speed Grade 5(30)			Transceiver Speed Grade 6			Transceiver Speed Grade 7			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Programmable ppm detector(46)	—	±62.5, 100, 125, 200, 250, 300, 500, and 1000									ppm
Run length	—	—	—	200	—	—	200	—	—	200	UI
Programmable equalization AC and DC gain	AC gain setting = 0 to 3 (47) DC gain setting = 0 to 1	Refer to *CTLE Response at Data Rates > 3.25 Gbps across Supported AC Gain and DC Gain for Cyclone V GX, GT, SX, and ST Devices* and *CTLE Response at Data Rates ≤ 3.25 Gbps across Supported AC Gain and DC Gain for Cyclone V GX, GT, SX, and ST Devices* diagrams.									dB

Table 24. Transmitter Specifications for Cyclone V GX, GT, SX, and ST Devices

Symbol/Description	Condition	Transceiver Speed Grade 5(30)			Transceiver Speed Grade 6			Transceiver Speed Grade 7			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Supported I/O standards	1.5 V PCML										
Data rate	—	614	—	5000/6144(35)	614	—	3125	614	—	2500	Mbps
V_{OCM} (AC coupled)	—	—	650	—	—	650	—	—	650	—	mV
Differential on-chip termination resistors	85-Ω setting	—	85	—	—	85	—	—	85	—	Ω
	100-Ω setting	—	100	—	—	100	—	—	100	—	Ω
	120-Ω setting	—	120	—	—	120	—	—	120	—	Ω
	150-Ω setting	—	150	—	—	150	—	—	150	—	Ω

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(45) $t_{LTR\_LTD\_manual}$ is the time the receiver CDR must be kept in lock to reference (LTR) mode after the `rx_is_lockedtoref` signal goes high when the CDR is functioning in the manual mode.

(46) The rate matcher supports only up to ±300 parts per million (ppm).

(47) The Intel Quartus Prime software allows AC gain setting = 3 for design with data rate between 614 Mbps and 1.25 Gbps only.

Typical TX V_{OD} Setting for Cyclone V Transceiver Channels with termination of 100 Ω

Table 27. Typical TX V_{OD} Setting for Cyclone V Transceiver Channels with termination of 100 Ω

Symbol	V_{OD} Setting(48)	V_{OD} Value (mV)	V_{OD} Setting(48)	V_{OD} Value (mV)
V_{OD} differential peak-to-peak typical	6(49)	120	34	680
	7(49)	140	35	700
	8(49)	160	36	720
	9	180	37	740
	10	200	38	760
	11	220	39	780
	12	240	40	800
	13	260	41	820
	14	280	42	840
	15	300	43	860
	16	320	44	880
	17	340	45	900
	18	360	46	920
	19	380	47	940
	20	400	48	960
	21	420	49	980
	22	440	50	1000
	23	460	51	1020
	24	480	52	1040

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(48) Convert these values to their binary equivalent form if you are using the dynamic reconfiguration mode for PMA analog controls.

(49) Only valid for data rates ≤ 5 Gbps.

Symbol	V_{OD} Setting[48]	V_{OD} Value (mV)	V_{OD} Setting[48]	V_{OD} Value (mV)
	25	500	53	1060
	26	520	54	1080
	27	540	55	1100
	28	560	56	1120
	29	580	57	1140
	30	600	58	1160
	31	620	59	1180
	32	640	60	1200
	33	660		

Transmitter Pre-Emphasis Levels

The following table lists the simulation data on the transmitter pre-emphasis levels in dB for the first post tap under the following conditions:

- Low-frequency data pattern—five 1s and five 0s
- Data rate—2.5 Gbps

The levels listed are a representation of possible pre-emphasis levels under the specified conditions only and the pre-emphasis levels may change with data pattern and data rate.

Cyclone V devices only support 1st post tap pre-emphasis with the following conditions:

- The 1st post tap pre-emphasis settings must satisfy $|B| + |C| \leq 60$ where $|B| = V_{OD}$ setting with termination value, $R_{TERM} = 100\ \Omega$ and $|C|$ = 1st post tap pre-emphasis setting.
- $|B| - |C| > 5$ for data rates < 5 Gbps and $|B| - |C| > 8.25$ for data rates > 5 Gbps.
- $(V_{MAX}/V_{MIN} - 1)\% < 600\%$, where $V_{MAX} = |B| + |C|$ and $V_{MIN} = |B| - |C|$.

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(48) Convert these values to their binary equivalent form if you are using the dynamic reconfiguration mode for PMA analog controls.

Transceiver Compliance Specification

The following table lists the physical medium attachment (PMA) specification compliance of all supported protocol for Cyclone V GX, GT, SX, and ST devices. For more information about the protocol parameter details and compliance specifications, contact your Intel Sales Representative.

Table 29. Transceiver Compliance Specification for All Supported Protocol for Cyclone V GX, GT, SX, and ST Devices

Protocol	Sub-protocol	Data Rate (Mbps)
PCIe	PCIe Gen1	2,500
	PCIe Gen2(50)	5,000
	PCIe Cable	2,500
XAUI	XAUI 2135	3,125
Serial RapidIO® (SRIO)	SRIO 1250 SR	1,250
	SRIO 1250 LR	1,250
	SRIO 2500 SR	2,500
	SRIO 2500 LR	2,500
	SRIO 3125 SR	3,125
	SRIO 3125 LR	3,125
	SRIO 5000 SR	5,000
	SRIO 5000 MR	5,000
	SRIO 5000 LR	5,000
Common Public Radio Interface (CPRI)	CPRI E6LV	614.4
	CPRI E6HV	614.4
	CPRI E6LVII	614.4

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(50) For PCIe Gen2 sub-protocol, Intel recommends increasing the V_{CCE_GXBL} and V_{CCL_GXBL} typical value from 1.1 V to 1.2 V for Cyclone V GT and ST FPGA systems which ensure full compliance to the PCIe Gen2 transmit jitter specification. For more information about the maximum full duplex channels recommended in Cyclone V GT and ST devices under this condition, refer to the *Transceiver Protocol Configurations in Cyclone V Devices* chapter.

Symbol	Parameter	Condition	Min	Typ	Max	Unit
		–C8, –A7 speed grades	600	—	1300	MHz
$t_{EINDUTY}$	Input clock or external feedback clock input duty cycle	—	40	—	60	%
f_{OUT}	Output frequency for internal global or regional clock	–C6, –C7, –I7 speed grades	—	—	550(54)	MHz
		–C8, –A7 speed grades	—	—	460(54)	MHz
f_{OUT_EXT}	Output frequency for external clock output	–C6, –C7, –I7 speed grades	—	—	667(54)	MHz
		–C8, –A7 speed grades	—	—	533(54)	MHz
$t_{OUTDUTY}$	Duty cycle for external clock output (when set to 50%)	—	45	50	55	%
t_{FCOMP}	External feedback clock compensation time	—	—	—	10	ns
$t_{DYCONFIGCLK}$	Dynamic configuration clock for `mgmt_clk` and `scanclk`	—	—	—	100	MHz
t_{LOCK}	Time required to lock from end-of-device configuration or deassertion of `areset`	—	—	—	1	ms
t_{DLOCK}	Time required to lock dynamically (after switchover or reconfiguring any non-post-scale counters/delays)	—	—	—	1	ms
f_{CLBW}	PLL closed-loop bandwidth	Low	—	0.3	—	MHz
		Medium	—	1.5	—	MHz
		High(55)	—	4	—	MHz
t_{PLL_PSERR}	Accuracy of PLL phase shift	—	—	—	±50	ps

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(53) The VCO frequency reported by the Intel Quartus Prime software takes into consideration the VCO post-scale counter K value. Therefore, if the counter K has a value of 2, the frequency reported can be lower than the f_{VCO} specification.

(54) This specification is limited by the lower of the two: I/O f_{MAX} or F_{OUT} of the PLL.

(55) High bandwidth PLL settings are not supported in external feedback mode.

Symbol		Condition	–C6			–C7, –I7			–C8, –A7			Unit
			Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
		SERDES factor J = 1 to 2, uses DDR registers	(65)	—	(66)	(65)	—	(66)	(65)	—	(66)	Mbps
	Emulated Differential I/O Standards with Three External Output Resistor Networks- f_{HSDR} (data rate)(67)	SERDES factor J = 4 to 10	(65)	—	640	(65)	—	640	(65)	—	550	Mbps
	Emulated Differential I/O Standards with One External Output Resistor Network - f_{HSDR} (data rate)	SERDES factor J = 4 to 10	(65)	—	170	(65)	—	170	(65)	—	170	Mbps
	$t_{x\ Jitter}$ -True Differential I/O Standards(67)	Total Jitterfor Data Rate, 600 Mbps – 840 Mbps	—	—	350	—	—	380	—	—	500	ps
		Total Jitter for Data Rate < 600Mbps	—	—	0.21	—	—	0.23	—	—	0.30	UI
	$t_{x\ Jitter}$ -Emulated Differential I/O Standards with Three External Output Resistor Networks	Total Jitter for Data Rate < 640Mbps	—	—	500	—	—	500	—	—	500	ps
	$t_{x\ Jitter}$ -Emulated Differential I/O Standards with One External Output Resistor Network	Total Jitter for Data Rate < 640Mbps	—	—	0.15	—	—	0.15	—	—	0.15	UI
	t_{DUTY}	TX output clock duty cycle for both True and	45	50	55	45	50	55	45	50	55	%

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(66) The maximum ideal data rate is the SERDES factor (J) × PLL max output frequency (f_{out}), provided you can close the design timing and the signal integrity simulation is clean. You can estimate the achievable maximum data rate by performing link timing closure analysis. You must consider the board skew margin, transmitter delay margin, and receiver sampling margin to determine the maximum data rate supported.

(67) You must calculate the leftover timing margin in the receiver by performing link timing closure analysis. You must consider the board skew margin, transmitter channel-to-channel skew, and receiver sampling margin to determine the leftover timing margin.

Symbol		Condition	–C6			–C7, –I7			–C8, –A7			Unit
			Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
		Emulated Differential I/O Standards										
	t_{RISE} and t_{FALL}	True Differential I/O Standards	—	—	200	—	—	200	—	—	200	ps
		Emulated Differential I/O Standards with Three External Output Resistor Networks	—	—	250	—	—	250	—	—	300	ps
		Emulated Differential I/O Standards with One External Output Resistor Network	—	—	300	—	—	300	—	—	300	ps
	TCCS	True Differential I/O Standards	—	—	200	—	—	250	—	—	250	ps
		Emulated Differential I/O Standards with Three External Output Resistor Networks	—	—	300	—	—	300	—	—	300	ps
		Emulated Differential I/O Standards with One External Output Resistor Network	—	—	300	—	—	300	—	—	300	ps
Receiver	f_{HSDR} (data rate)	SERDES factor J =4 to 10(64)	(65)	—	875(67)	(65)	—	840(67)	(65)	—	640(67)	Mbps
		SERDES factor J = 1 to 2, uses DDR registers	(65)	—	(66)	(65)	—	(66)	(65)	—	(66)	Mbps
Sampling Window		—	—	—	350	—	—	350	—	—	350	ps

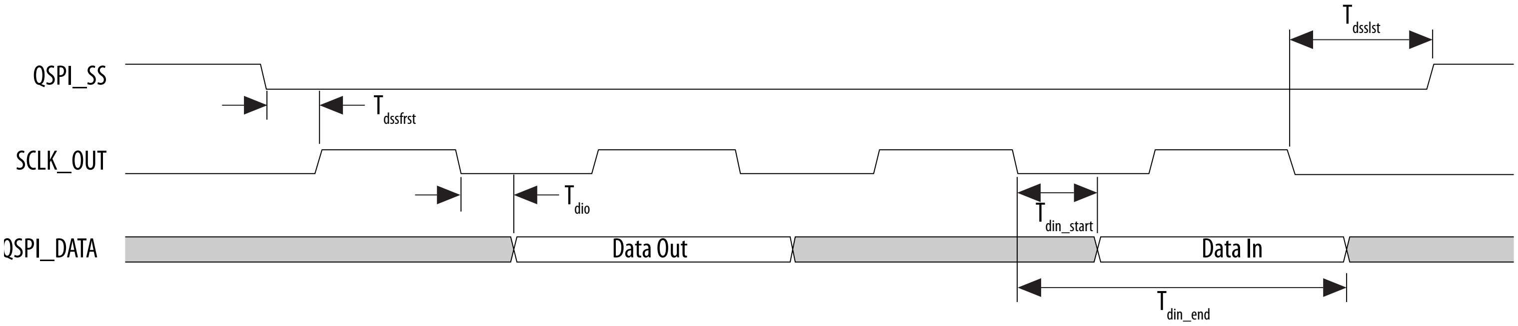
Quad SPI Flash Timing Characteristics

Table 43. Quad Serial Peripheral Interface (SPI) Flash Timing Requirements for Cyclone V Devices

Symbol	Description	Min	Typ	Max	Unit
F_{clk}	SCLK_OUT clock frequency (External clock)	—	—	108	MHz
T_{qspi_clk}	QSPI_CLK clock period (Internal reference clock)	2.32	—	—	ns
$T_{dutycycle}$	SCLK_OUT duty cycle	45	—	55	%
$T_{dssfrst}$	Output delay QSPI_SS valid before first clock edge	—	1/2 cycle of SCLK_OUT	—	ns
T_{dsslst}	Output delay QSPI_SS valid after last clock edge	–1	—	1	ns
T_{dio}	I/O data output delay	–1	—	1	ns
T_{din_start}	Input data valid start	—	—	$(2 + R_{delay}) \times T_{qspi\_clk} - 7.52$ (68)	ns
T_{din_end}	Input data valid end	$(2 + R_{delay}) \times T_{qspi\_clk} - 1.21$ (68)	—	—	ns

Figure 6. Quad SPI Flash Timing Diagram

This timing diagram illustrates clock polarity mode 0 and clock phase mode 0.



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(68) R_{delay} is set by programming the register `qspiregs.rddatacap`. For the SoC EDS software version 13.1 and later, Intel provides automatic Quad SPI calibration in the preloader. For more information about R_{delay}, refer to the *Quad SPI Flash Controller chapter in the Cyclone V Hard Processor System Technical Reference Manual*.

Related Information

Quad SPI Flash Controller Chapter, Cyclone V Hard Processor System Technical Reference Manual
Provides more information about R_{delay}.

SPI Timing Characteristics

Table 44. SPI Master Timing Requirements for Cyclone V Devices

The setup and hold times can be used for Texas Instruments SSP mode and National Semiconductor Microwire mode.

Symbol	Description	Min	Max	Unit
T_{clk}	CLK clock period	16.67	—	ns
T_{su}	SPI Master-in slave-out (MISO) setup time	8.35 (69)	—	ns
T_h	SPI MISO hold time	1	—	ns
$T_{dutycycle}$	SPI_CLK duty cycle	45	55	%
$T_{dssfrst}$	Output delay SPI_SS valid before first clock edge	8	—	ns
T_{dsslst}	Output delay SPI_SS valid after last clock edge	8	—	ns
T_{dio}	Master-out slave-in (MOSI) output delay	–1	1	ns

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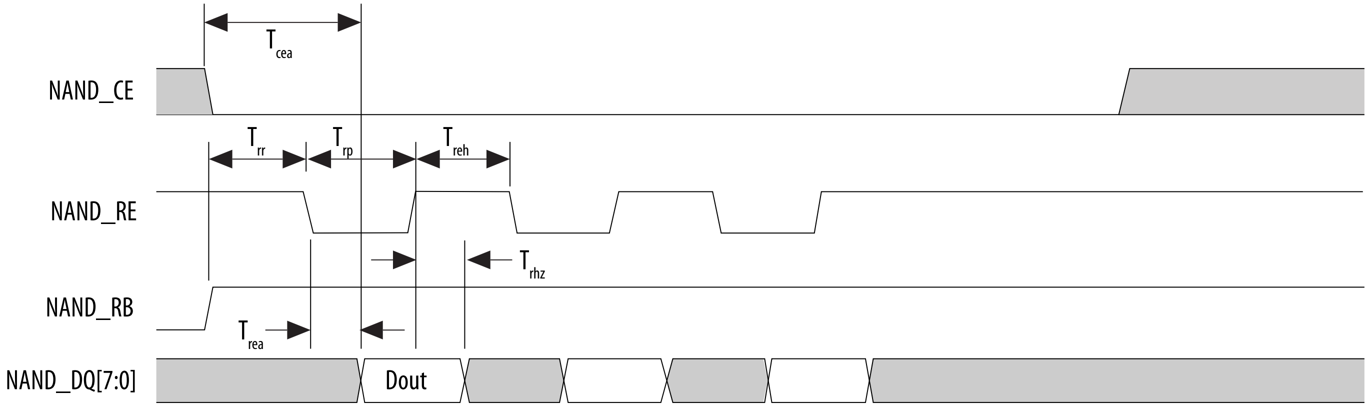
(69) This value is based on `rx_sample_dly` = 1 and `spi_m_clk` = 120 MHz. `spi_m_clk` is the internal clock that is used by SPI Master to derive it’s SCLK_OUT. These timings are based on `rx_sample_dly` of 1. This delay can be adjusted as needed to accommodate slower response times from the slave. Note that a delay of 0 is not allowed. The setup time can be used as a reference starting point. It is very crucial to do a calibration to get the correct `rx_sample_dly` value because each SPI slave device may have different output delay and each application board may have different path delay. For more information about `rx_sample_delay`, refer to the *SPI Controller* chapter in the *Hard Processor System Technical Reference Manual*.

Figure 18. NAND Data Read Timing Diagram



Arm Trace Timing Characteristics

Table 53. Arm Trace Timing Requirements for Cyclone V Devices

Most debugging tools have a mechanism to adjust the capture point of trace data.

Description	Min	Max	Unit
CLK clock period	12.5	—	ns
CLK maximum duty cycle	45	55	%
CLK to D0 –D7 output data delay	–1	1	ns

UART Interface

The maximum UART baud rate is 6.25 megasymbols per second.

GPIO Interface

The minimum detectable general-purpose I/O (GPIO) pulse width is 2 µs. The pulse width is based on a debounce clock frequency of 1 MHz.

Symbol	Parameter	Minimum	Maximum	Unit
t_{CF2CK}(83)	`nCONFIG` high to first rising edge on DCLK	1506	—	µs
t_{ST2CK}(83)	nSTATUS high to first rising edge of DCLK	2	—	µs
t_{DSU}	`DATA[]` setup time before rising edge on DCLK	5.5	—	ns
t_{DH}	`DATA[]` hold time after rising edge on DCLK	$N - 1/f_{DCLK}$(84)	—	s
t_{CH}	DCLK high time	$0.45 \times 1/f_{MAX}$	—	s
t_{CL}	DCLK low time	$0.45 \times 1/f_{MAX}$	—	s
t_{CLK}	DCLK period	$1/f_{MAX}$	—	s
f_{MAX}	DCLK frequency (FPP ×8/ ×16)	—	125	MHz
t_R	Input rise time	—	40	ns
t_F	Input fall time	—	40	ns
t_{CD2UM}	`CONF_DONE` high to user mode(85)	175	437	µs
t_{CD2CU}	`CONF_DONE` high to CLKUSR enabled	4 × maximum DCLK period	—	—
t_{CD2UMC}	`CONF_DONE` high to user mode with CLKUSR option on	$t_{CD2CU} + (T_{init} \times$ CLKUSR period)	—	—
T_{init}	Number of clock cycles required for device initialization	8,576	—	Cycles

Related Information

FPP Configuration Timing

Provides the FPP configuration timing waveforms.

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(82) This value can be obtained if you do not delay configuration by externally holding nSTATUS low.

(83) If nSTATUS is monitored, follow the t_{ST2CK} specification. If nSTATUS is not monitored, follow the t_{CF2CK} specification.

(84) N is the DCLK-to-`DATA[]` ratio and f_{DCLK} is the DCLK frequency of the system.

(85) The minimum and maximum numbers apply only if you chose the internal oscillator as the clock source for initializing the device.

Variant	Member Code	Configuration .rbf Size (bits)	IOCSR .rbf Size (bits)	Recommended EPCQ Serial Configuration Device(94)
	A4	33,958,560	322,072	EPCQ128
	A5	56,057,632	324,888	EPCQ128
	A6	56,057,632	324,888	EPCQ128
Cyclone V SX	C2	33,958,560	322,072	EPCQ128
	C4	33,958,560	322,072	EPCQ128
	C5	56,057,632	324,888	EPCQ128
	C6	56,057,632	324,888	EPCQ128
Cyclone V ST	D5	56,057,632	324,888	EPCQ128
	D6	56,057,632	324,888	EPCQ128

Minimum Configuration Time Estimation

Table 65. Minimum Configuration Time Estimation for Cyclone V Devices

The estimated values are based on the configuration `.rbf` sizes in *Uncompressed .rbf Sizes for Cyclone V Devices* table.

Variant	Member Code	Active Serial(96)			Fast Passive Parallel(97)		
		Width	DCLK (MHz)	Minimum Configuration Time (ms)	Width	DCLK (MHz)	Minimum Configuration Time (ms)
Cyclone V E	A2	4	100	53	16	125	11
	A4	4	100	53	16	125	11
	A5	4	100	85	16	125	17
	A7	4	100	140	16	125	28

continued...

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(94) The recommended EPCQ serial configuration devices are able to store more than one image.

(96) DCLK frequency of 100 MHz using external CLKUSR.

(97) Maximum FPGA FPP bandwidth may exceed bandwidth available from some external storage or control logic.

Programmable Output Buffer Delay

Table 69. Programmable Output Buffer Delay for Cyclone V Devices

This table lists the delay chain settings that control the rising and falling edge delays of the output buffer.

You can set the programmable output buffer delay in the Intel Quartus Prime software by setting the **Output Buffer Delay Control** assignment to either positive, negative, or both edges, with the specific values stated here (in ps) for the **Output Buffer Delay** assignment.

Symbol	Parameter	Typical	Unit
D_{OUTBUF}	Rising and/or falling edge delay	0 (default)	ps
		50	ps
		100	ps
		150	ps

Glossary

Table 70. Glossary

Term	Definition
Differential I/O standards	Receiver Input Waveforms

continued...